



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

David J. Corisis

Serial No.: 09/342,789

Filed: June 29, 1999

For: CHIP SCALE PACKAGE WITH  
HEAT SPREADER AND METHOD OF  
MANUFACTURE

Confirmation No.: 7096

Examiner: D. Graybill

Group Art Unit: 2827

Attorney Docket No.: 2269-3384.1US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

February 7, 2003  
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3/4/03

TRANSMITTAL OF FORMAL DRAWINGS

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Attached please find the formal drawings for this application.

Respectfully submitted,

*James R. Duzan*

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